

Integrated Silicon Pressure Sensor On-Chip Signal Conditioned, Temperature Compensated and Calibrated

The MPXV5004G series piezoresistive transducer is a state-of-the-art monolithic silicon pressure sensor designed for a wide range of applications, but particularly those employing a microcontroller or microprocessor with A/D inputs. This sensor combines a highly sensitive implanted strain gauge with advanced micromachining techniques, thin-film metallization, and bipolar processing to provide an accurate, high level analog output signal that is proportional to the applied pressure.

Features

- Temperature Compensated over 10° to 60°C
- Available in Gauge Surface Mount (SMT) or Through-hole (DIP) Configurations
- Durable Thermoplastic (PPS) Package

Application Examples

- Washing Machine Water Level
- Ideally Suited for Microprocessor or Microcontroller-Based Systems

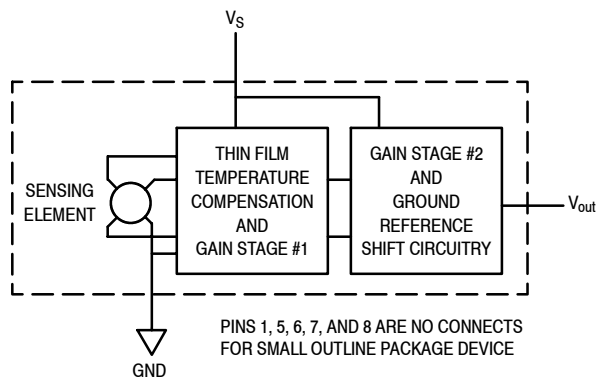
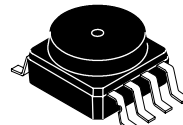


Figure 1. Fully Integrated Pressure Sensor Schematic

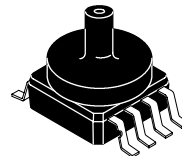
MPXV5004G SERIES

**INTEGRATED
 PRESSURE SENSOR**
 0 to 3.92 kPa
 (0 to 400 mm H₂O)
 1.0 to 4.9 V OUTPUT

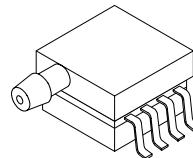
SMALL OUTLINE PACKAGE SURFACE MOUNT



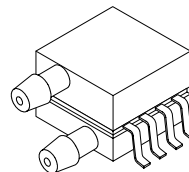
MPXV5004G6U
 CASE 482



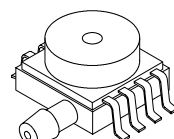
MPXV5004GC6U
 CASE 482A



MPXV5004GP
 CASE 1369

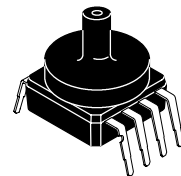


MPXV5004DP
 CASE 1351

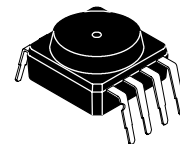


MPXV5004GVP
 CASE 1368

SMALL OUTLINE PACKAGE THROUGH-HOLE



MPXV5004GC7U
 CASE 482C



MPXV5004G7U
 CASE 482B

PIN NUMBER

1	N/C	5	N/C
2	V _S	6	N/C
3	Gnd	7	N/C
4	V _{out}	8	N/C

NOTE: Pins 1, 5, 6, 7, and 8 are internal device connections. Do not connect to external circuitry or ground. Pin 1 is noted by the notch in the lead.

MAXIMUM RATINGS(NOTE)

Parameters	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	P _{max}	16	kPa
Storage Temperature	T _{stg}	-30 to +100	°C
Operating Temperature	T _A	0 to +85	°C

NOTE: Exposure beyond the specified limits may cause permanent damage or degradation to the device.

OPERATING CHARACTERISTICS (V_S = 5.0 Vdc, T_A = 25°C unless otherwise noted, P1 > P2. Decoupling circuit shown in Figure 3 required to meet electrical specifications)

Characteristic	Symbol	Min	Typ	Max	Unit	
Pressure Range	P _{OP}	0	—	3.92 400	kPa mm H ₂ O	
Supply Voltage ⁽¹⁾	V _S	4.75	5.0	5.25	Vdc	
Supply Current	I _S	—	—	10	mAdc	
Span at 306 mm H ₂ O (3 kPa) ⁽²⁾	V _{FSS}	—	3.0	—	V	
Offset ⁽³⁾⁽⁵⁾	V _{off}	0.75	1.00	1.25	V	
Sensitivity	V/P	—	1.0 9.8	—	V/kPa mV/mm H ₂ O	
Accuracy ⁽⁴⁾⁽⁵⁾	0 to 100 mm H ₂ O 100 to 400 mm H ₂ O	(10 to 60°C) (10 to 60°C)	—	—	—	±1.5 ±2.5 %V _{FSS} %V _{FSS}

NOTES:

- Device is ratiometric within this specified excitation range.
- Span is defined as the algebraic difference between the output voltage at specified pressure and the output voltage at the minimum rated pressure.
- Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
- Accuracy (error budget) consists of the following:
 - Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.
 - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
 - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C.
 - Offset Stability: Output deviation, after 1000 temperature cycles, -30 to 100°C, and 1.5 million pressure cycles, with minimum rated pressure applied.
 - TcSpan: Output deviation over the temperature range of 10 to 60°C, relative to 25°C.
 - TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 10 to 60°C, relative to 25°C.
 - Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of V_{FSS}, at 25°C.
- Auto Zero at Factory Installation: Due to the sensitivity of the MPXV5004G, external mechanical stresses and mounting position can affect the zero pressure output reading. Autozeroing is defined as storing the zero pressure output reading and subtracting this from the device's output during normal operations. Reference AN1636 for specific information. The specified accuracy assumes a maximum temperature change of ± 5° C between autozero and measurement.

ON-CHIP TEMPERATURE COMPENSATION, CALIBRATION AND SIGNAL CONDITIONING

The performance over temperature is achieved by integrating the shear-stress strain gauge, temperature compensation, calibration and signal conditioning circuitry onto a single monolithic chip.

Figure 2 illustrates the gauge configuration in the basic chip carrier (Case 482). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

The MPXV5004G series sensor operating characteristics are based on use of dry air as pressure media. Media, other than dry air, may have adverse effects on sensor performance and long-term reliability. Internal reliability and qualification

test for dry air, and other media, are available from the factory. Contact the factory for information regarding media tolerance in your application.

Figure 3 shows the recommended decoupling circuit for interfacing the output of the MPXV5004G to the A/D input of the microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

Figure 4 shows the sensor output signal relative to pressure input. Typical, minimum and maximum output curves are shown for operation over a temperature range of 10°C to 60°C using the decoupling circuit shown in Figure 3. The output will saturate outside of the specified pressure range.

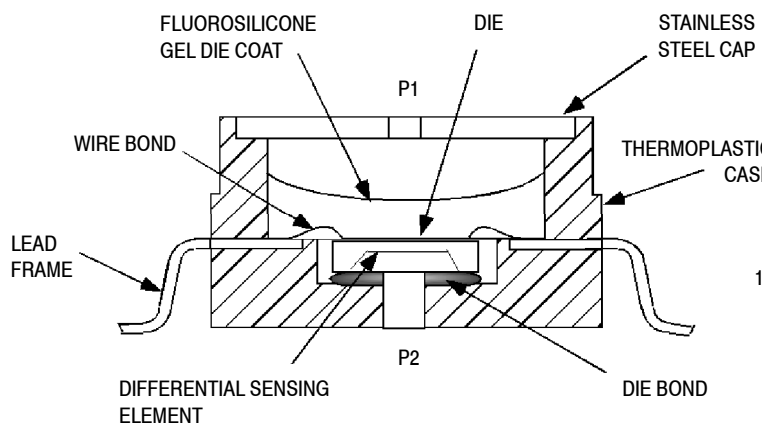


Figure 2. Cross-Sectional Diagram (Not to Scale)

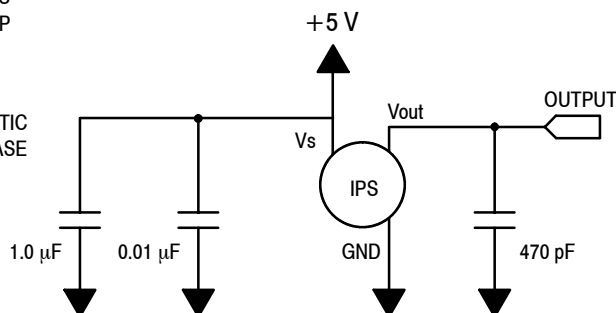


Figure 3. Recommended power supply decoupling and output filtering.

For additional output filtering, please refer to Application Note AN1646.

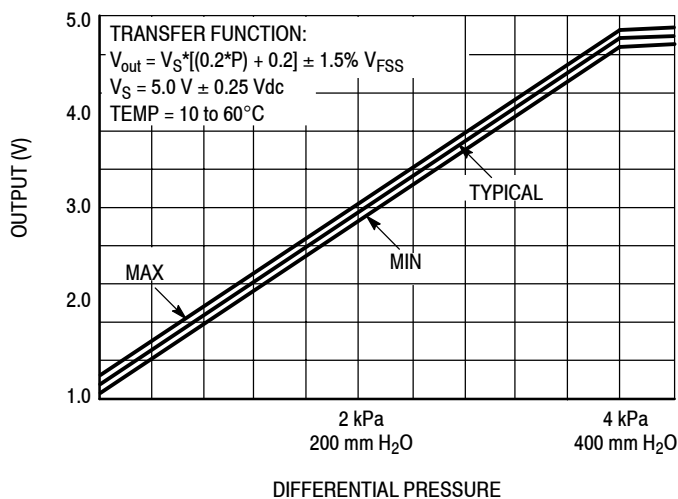


Figure 4. Output versus Pressure Differential

(See Note 5 in Operating Characteristics)

PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

Freescale Semiconductor designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing silicone gel which isolates the die from the environment. The

Freescale Semiconductor pressure sensor is designed to operate with positive differential pressure applied, $P1 > P2$.

The Pressure (P1) side may be identified by using the table below:

Part Number	Case Type	Pressure (P1) Side Identifier
MPXV5004GC6U/T1	482A	Side with Port Attached
MPXV5004G6U/T1	482	Stainless Steel Cap
MPXV5004GC7U	482C	Side with Port Attached
MPXV5004G7U	482B	Stainless Steel Cap
MPXV5004GP	1369	Side with Port Attached
MPXV5004DP	1351	Side with Port Marking
MPXV5004GVP	1368	Stainless Steel Cap

ORDERING INFORMATION

MPXV5004G series pressure sensors are available in the basic element package or with a pressure port. Two packing options are offered for the surface mount configuration.

Device Type / Order No.	Case No.	Packing Options	Device Marking
MPXV5004G6U	482	Rails	MPXV5004G
MPXV5004G6T1	482	Tape and Reel	MPXV5004G
MPXV5004GC6U	482A	Rails	MPXV5004G
MPXV5004GC6T1	482A	Tape and Reel	MPXV5004G
MPXV5004GC7U	482C	Rails	MPXV5004G
MPXV5004G7U	482B	Rails	MPXV5004G
MPXV5004GP	1369	Trays	MPXV5004G
MPXV5004DP	1351	Trays	MPXV5004G
MPXV5004GVP	1368	Trays	MPXV5004G

INFORMATION FOR USING THE SMALL OUTLINE PACKAGE (CASE 482)

MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the surface mount packages must be the correct size to ensure proper solder connection interface between the board and the package. With the correct

footprint, the packages will self align when subjected to a solder reflow process. It is always recommended to design boards with a solder mask layer to avoid bridging and shorting between solder pads.

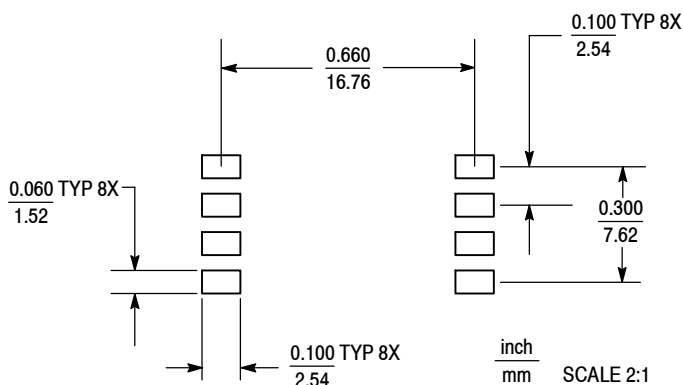
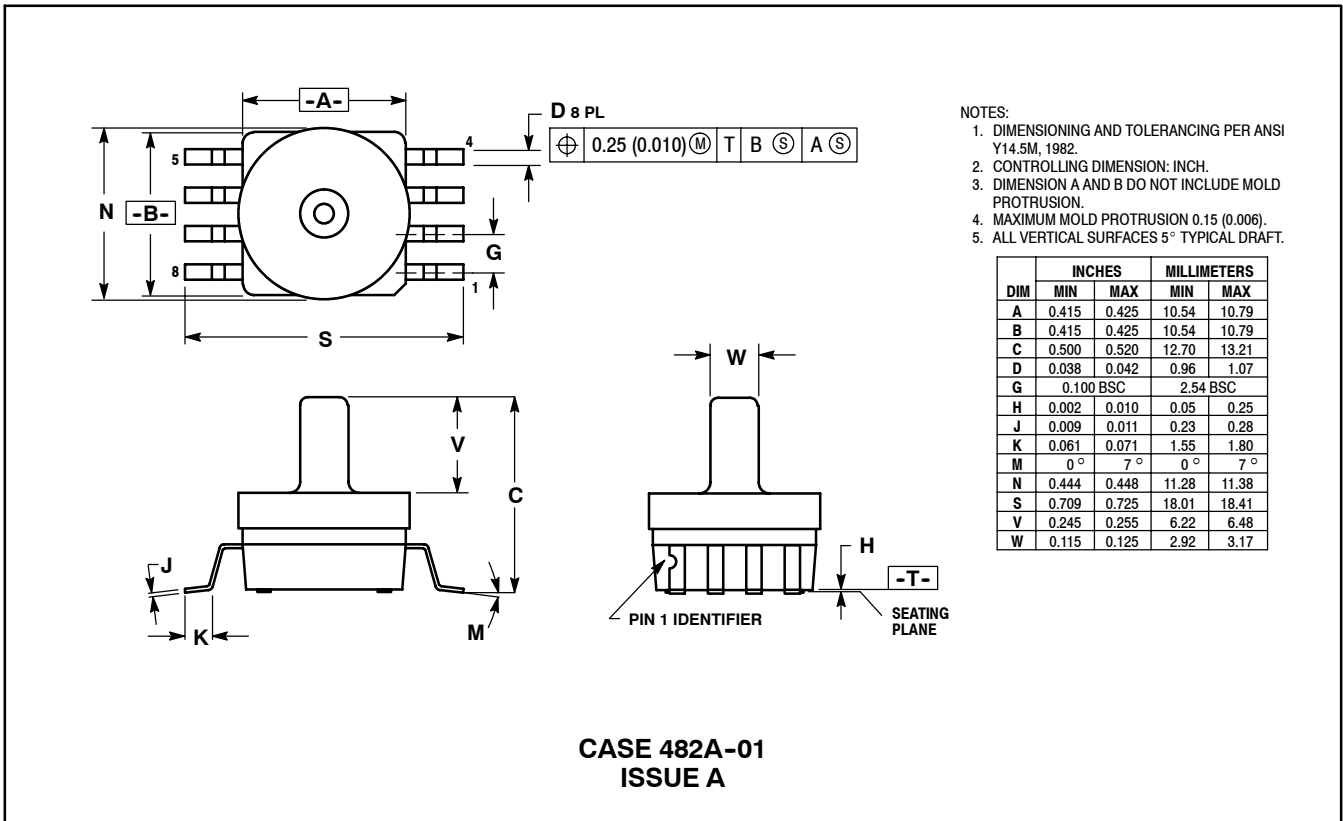
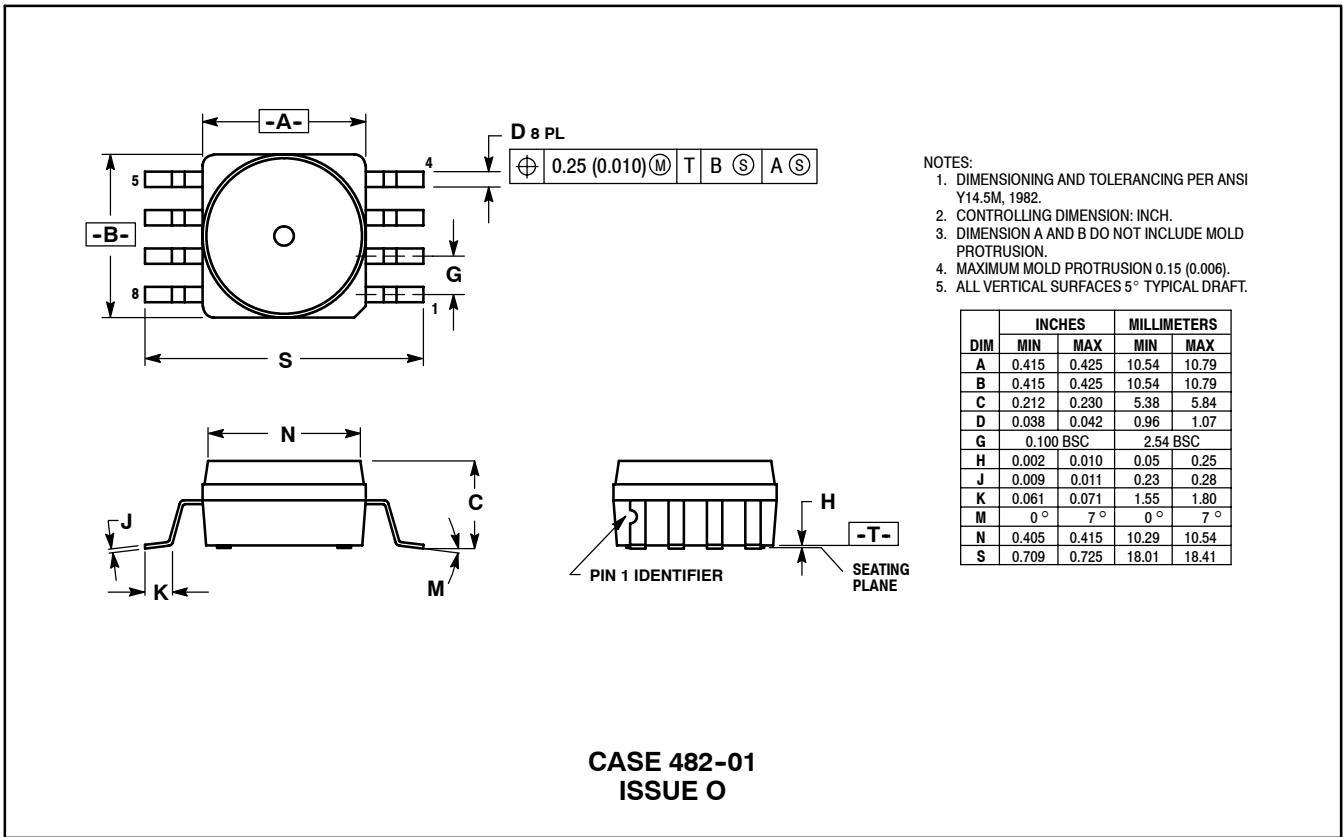


Figure 5. SOP Footprint (Case 482)

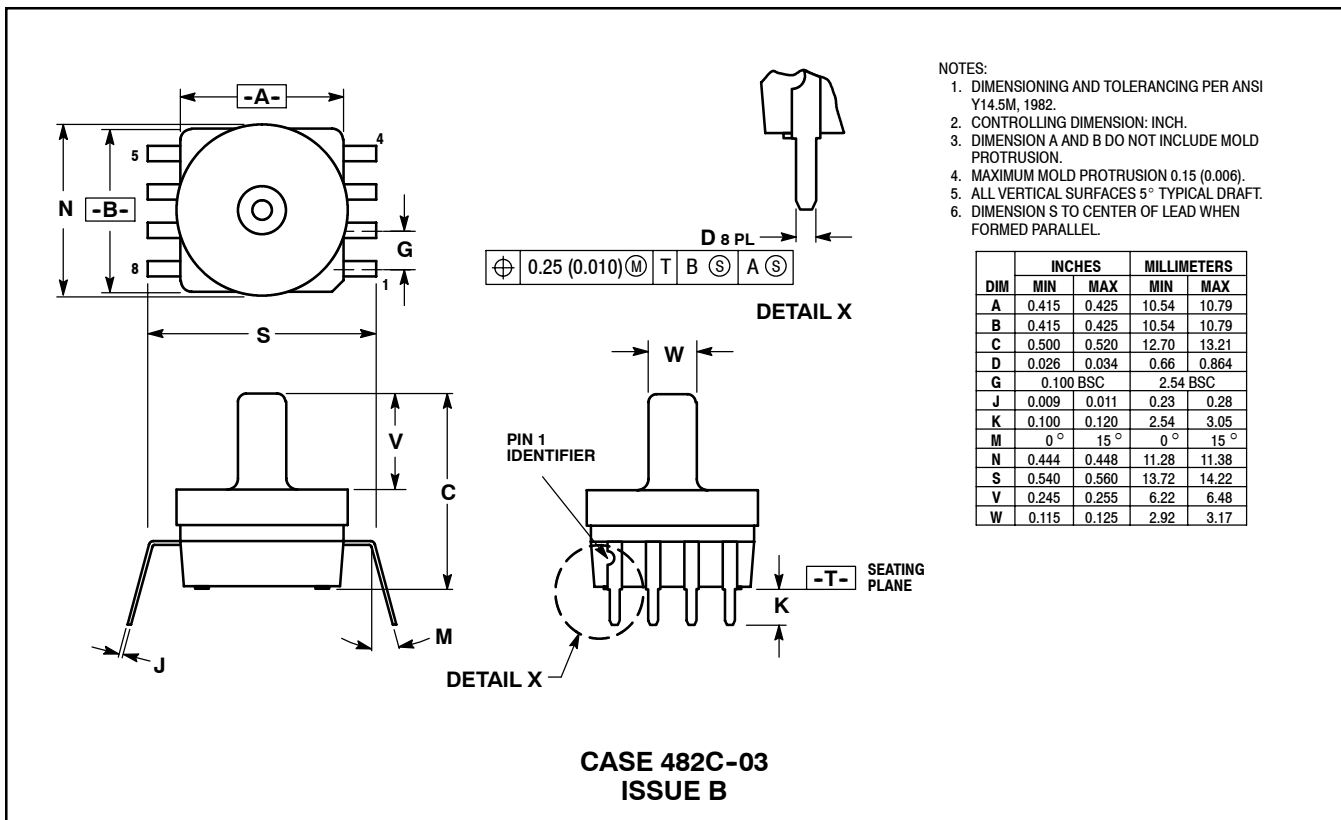
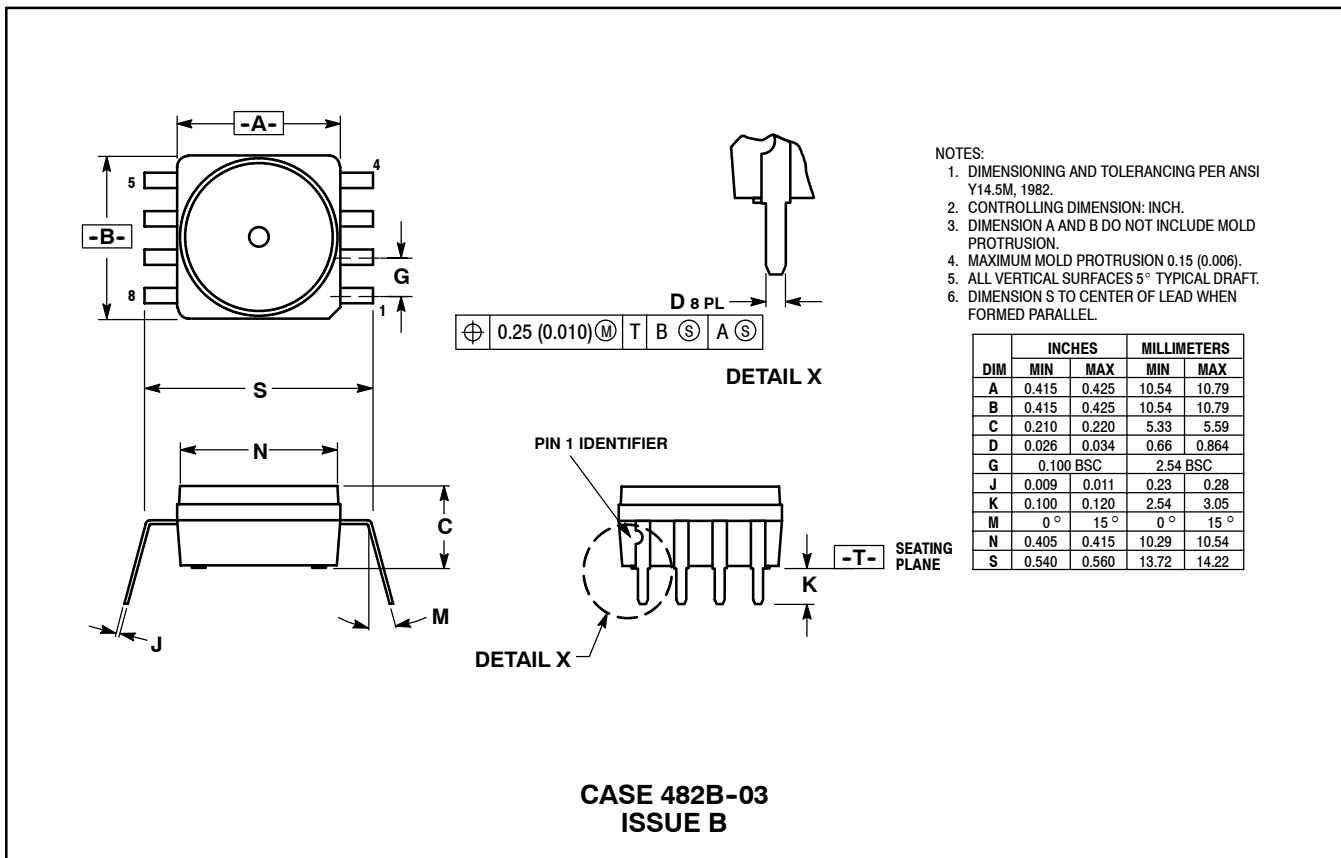
NOTES

NOTES

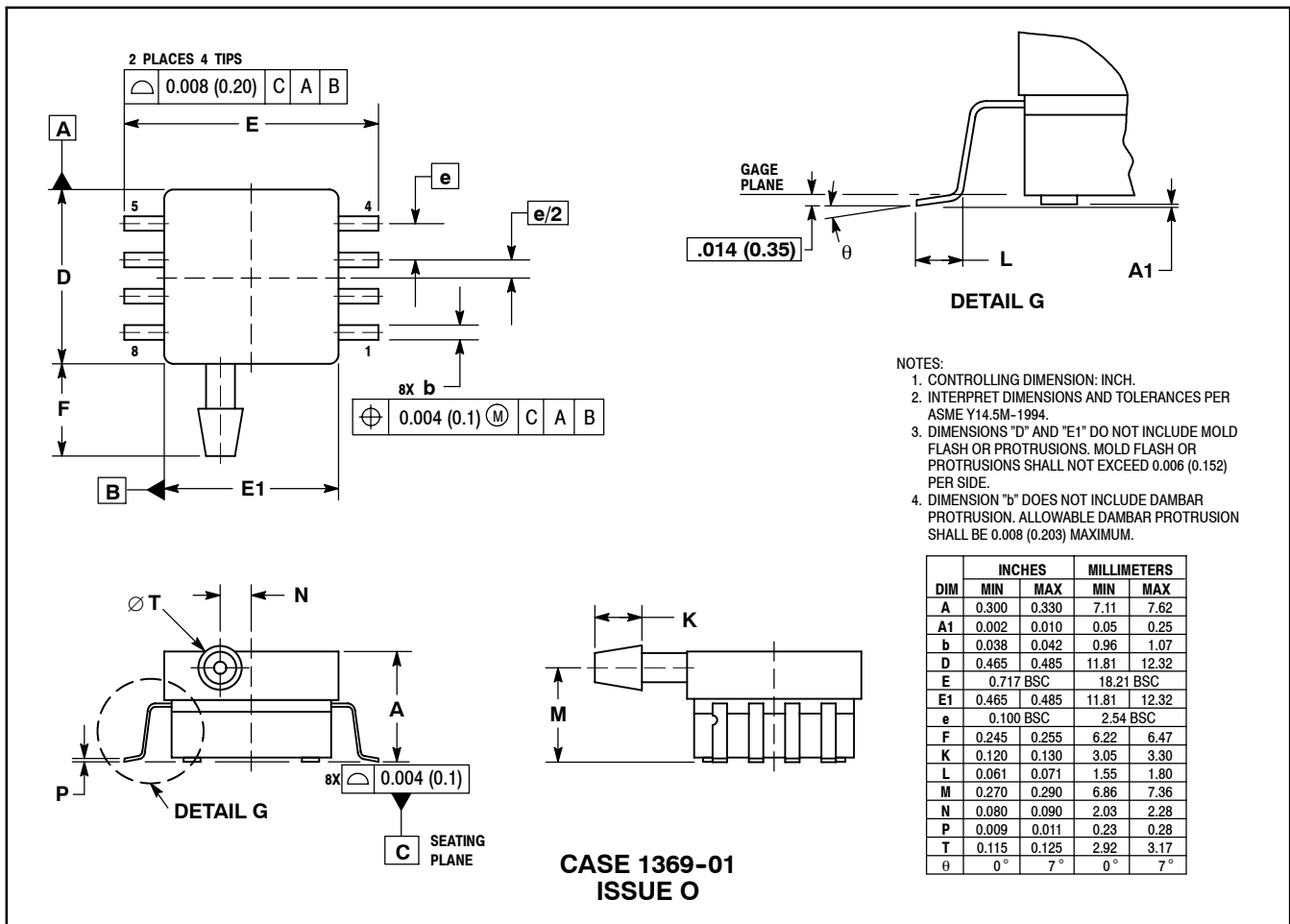
SMALL OUTLINE PACKAGE DIMENSIONS



SMALL OUTLINE PACKAGE DIMENSIONS (CONTINUED)

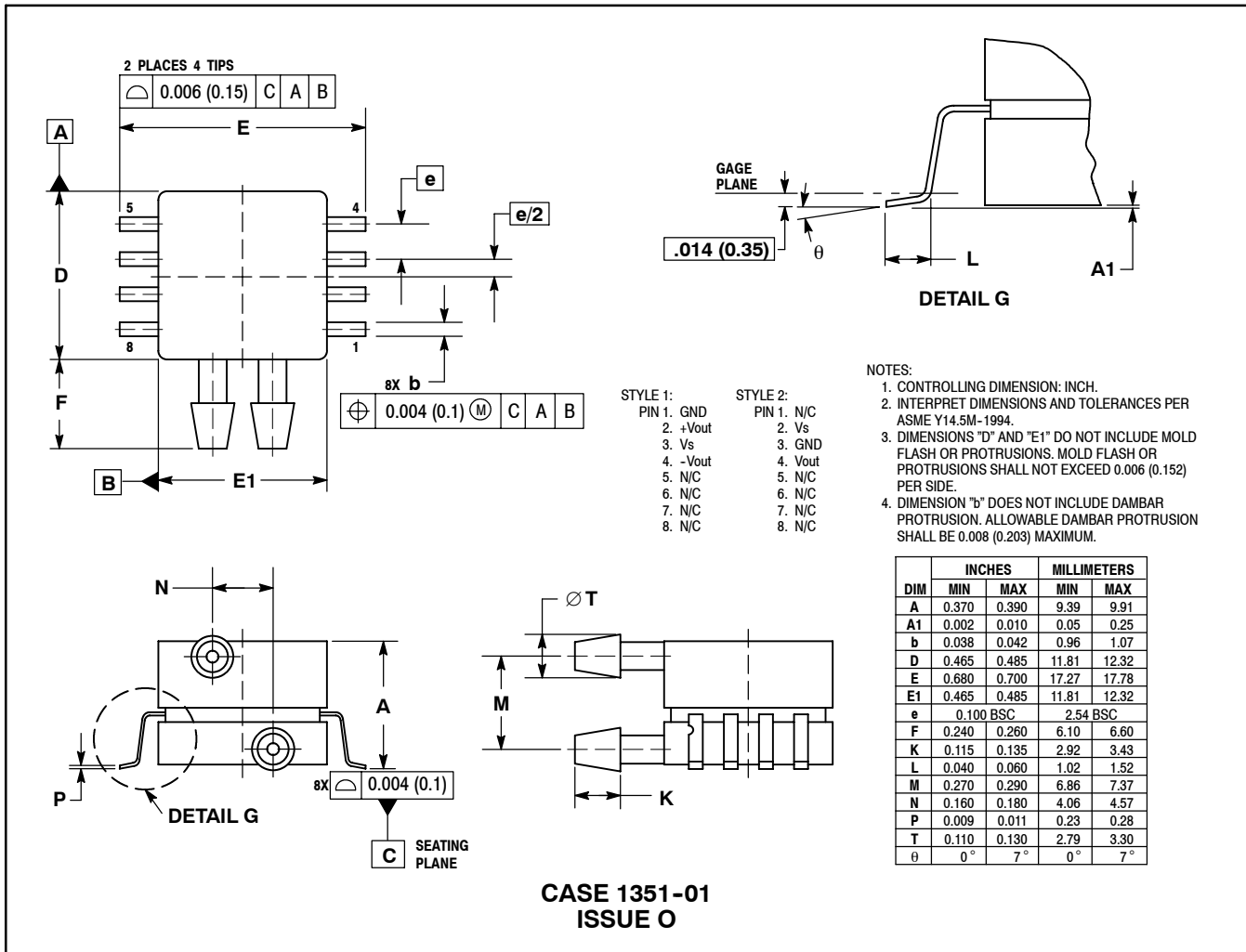


SMALL OUTLINE PACKAGE DIMENSIONS (CONTINUED)

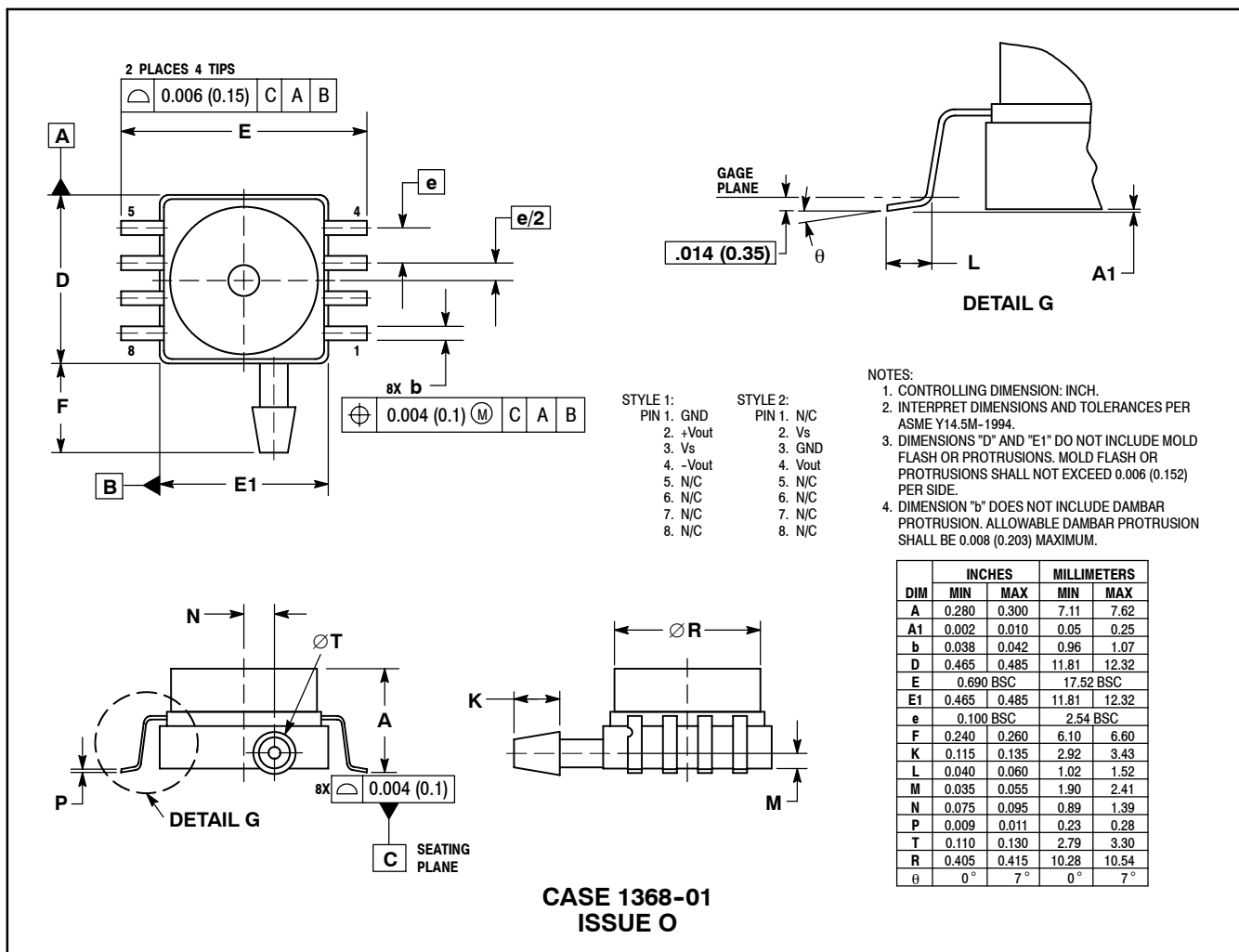


- NOTES:
1. CONTROLLING DIMENSION: INCH.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
 3. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 (0.152) PER SIDE.
 4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.008 (0.203) MAXIMUM.

SMALL OUTLINE PACKAGE DIMENSIONS (CONTINUED)



SMALL OUTLINE PACKAGE DIMENSIONS (CONTINUED)



How to Reach Us:

Home Page:

www.freescale.com

E-mail:

support@freescale.com

USA/Europe or Locations Not Listed:

Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
+1-800-521-6274 or +1-480-768-2130
support@freescale.com

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com

Japan:

Freescale Semiconductor Japan Ltd.
Technical Information Center
3-20-1, Minami-Azabu, Minato-ku
Tokyo 106-0047, Japan
0120 191014 or +81 3 3440 3569
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate
Tai Po, N.T., Hong Kong
+800 2666 8080
support.asia@freescale.com

For Literature Requests Only:

Freescale Semiconductor Literature Distribution Center
P.O. Box 5405
Denver, Colorado 80217
1-800-441-2447 or 303-675-2140
Fax: 303-675-2150
LDCForFreescaleSemiconductor@hibbertgroup.com

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc.
All other product or service names are the property of their respective owners.
© Freescale Semiconductor, Inc. 2004. All rights reserved.

